

ABSTRACT OF THE DISCLOSURE

In a method of forming a thick-film wiring on a substrate, photosensitive-electroconductive paste is filled into a pattern groove formed on the surface of a light-transmitting intaglio plate. The pattern groove corresponds to a desired thick-film wiring pattern. The photosensitive-electroconductive paste filled in the pattern groove are irradiated with light-rays from the front and back sides of the intaglio plate to cause the paste to harden until the overall peripheral surface of the electroconductive paste has a predetermined hardness. The electroconductive paste hardened in the pattern grooves of the intaglio plate is transferred to an intermediate piece. Then, the electroconductive paste is transferred from the intermediate piece to a substrate. Thereafter, the electroconductive paste is fired, whereby a thick-film wiring is formed on the substrate.